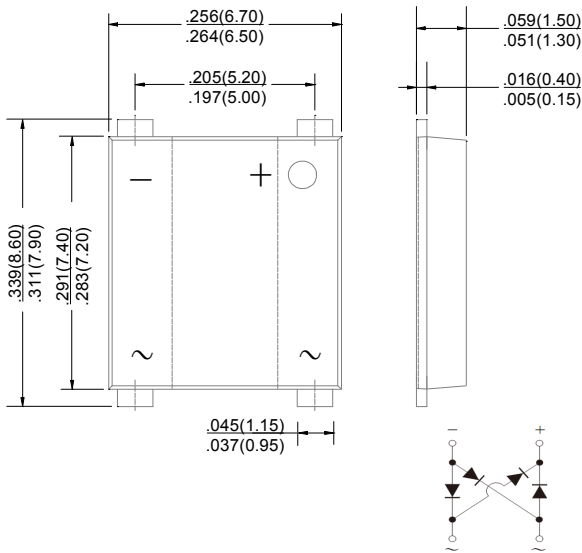


## Single Phase 3.0Amp Glass passivated Bridge Rectifiers

### UMSB



### Features

- The plastic package carries Underwriters Laboratory Flammability Classification 94V-0
- Idea for printed circuit board
- Glass passivated Junction chip
- Low reverse leakage
- High forward surge current capability
- High temperature soldering guaranteed  
250°C/10 seconds at terminals

### Mechanical Data

**Case :** Molded plastic body

**Terminals :** Solder plated, solderable per MIL-STD-750, Method 2026

**Polarity :** Polarity symbol marking on body

**Mounting Position :** Any

### Maximum Ratings And Electrical Characteristics

Ratings at 25°C ambient temperature unless otherwise specified. Single phase half-wave 60Hz, resistive or inductive load, for capacitive load current derate by 20%.

Parameter	SYMBOLS	MSB30A	MSB30B	MSB30D	MSB30G	MSB30J	MSB30K	MSB30M	UNITS
Maximum repetitive peak reverse voltage	$V_{RRM}$	50	100	200	400	600	800	1000	V
Maximum RMS voltage	$V_{RMS}$	35	70	140	280	420	560	700	V
Maximum DC blocking voltage	$V_{DC}$	50	100	200	400	600	800	1000	V
Maximum average forward rectified current at $T_L=100^\circ\text{C}$	$I_{(AV)}$	3.0							A
Peak forward surge current, 8.3ms single half sine-wave superimposed on rated load	$I_{FSM}$	120							A
Rating for fusing ( $t=8.3\text{ms}$ , $T_a=25^\circ\text{C}$ )	$I^2t$	59.76							$\text{A}^2\text{s}$
Maximum instantaneous forward voltage at 3.0A	$V_F$	1.10							V
Maximum DC reverse current $T_A=25^\circ\text{C}$ at rated DC blocking voltage $T_A=125^\circ\text{C}$	$I_R$	5.0 500							$\mu\text{A}$
Typical junction capacitance (Note 1)	$C_J$	33.0							pF
Typical thermal resistance	$R_{qJA}$	55.0							$^\circ\text{C}/\text{W}$
Operating junction and storage temperature range	$T_J, T_{STG}$	-55 to +150							$^\circ\text{C}$

**Note:** 1. Measured at 1MHz and applied reverse voltage of 4.0V D.C.

**Ratings And Characteristic Curves**

FIG. 1- DERATING CURVE OUTPUT RECTIFIED CURRENT

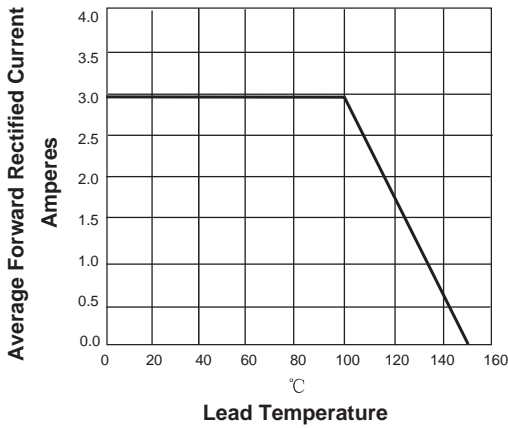


FIG. 2-MAXIMUM NON-REPETITIVE PEAK FORWARD SURGE CURRENT PER LEG

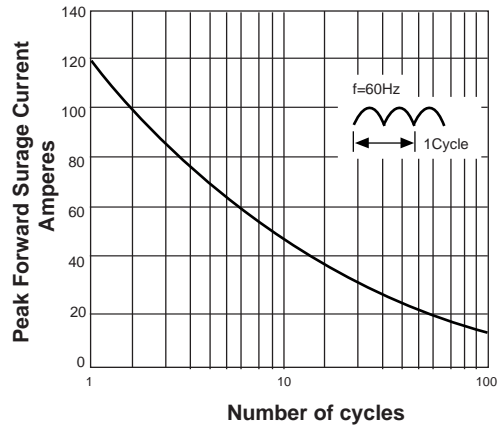


FIG. 3-TYPICAL FORWARD VOLTAGE CHARACTERISTICS

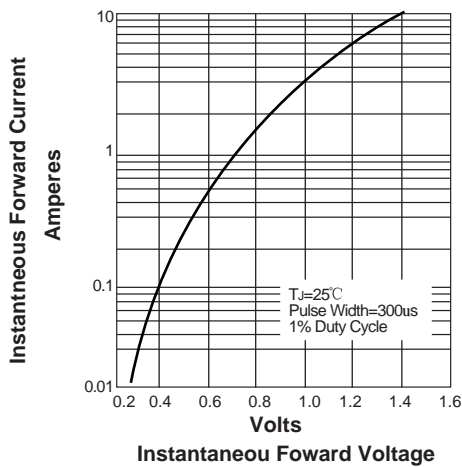
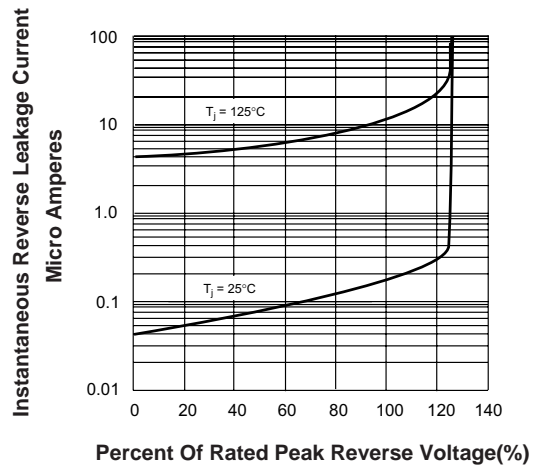
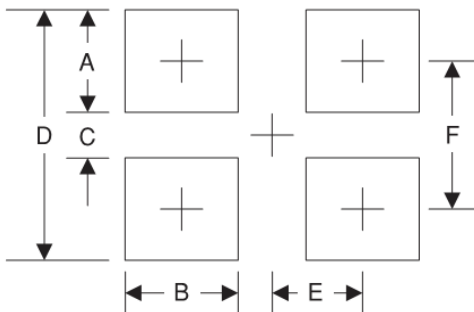


FIG. 4-TYPICAL REVERSE LEAKAGE CHARACTERISTICS

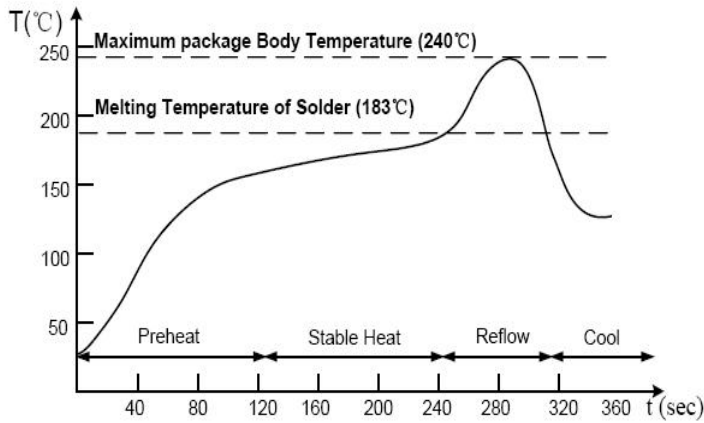


**Suggested Pad Layout**



Symbol	Unit (mm)	Unit (inch)
A	1.8	0.071
B	2.0	0.078
C	5.50	0.216
D	9.15	0.360
E	2.6	0.102
F	7.35	0.289

**Suggested Soldering Temperature Profile**

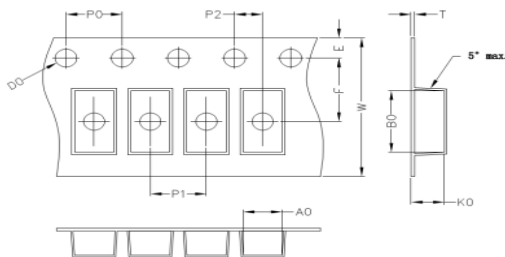


**Note**

- Recommended reflow methods: IR, vapor phase oven, hot air oven, wave solder.
- The device can be exposed to a maximum temperature of 265°C for 10 seconds.
- Devices can be cleaned using standard industry methods and solvents.
- If reflow temperatures exceed the recommended profile, devices may not meet the performance requirements.

**Package Information**

**Carrier Dimension(mm)**



<b>A0</b>	<b>B0</b>	<b>K0</b>	<b>D0</b>	<b>E</b>	<b>F</b>
6.90	8.60	1.65	1.55	1.75	7.50
<b>P0</b>	<b>P1</b>	<b>P2</b>	<b>T</b>	<b>W</b>	<b>Tolerance</b>
4.0	12.0	2.0	0.30	16	0.1

**Package Specifications**

Package	Reel Size	Reel DIA. (mm)	Q'TY/Reel (Kpcs)	Box Size (mm)	QTY/Box (Kpcs)	Carton Size (mm)	Q'TY/Carton (Kpcs)
MSBL	13'	330	3	338	6	365*365*360	48

单击下面可查看定价，库存，交付和生命周期等信息

[>>DIOS\(迪恩思\)](#)